

# Fair-Rite P/N **2773021447**

## 73 Material Grade

## Nominal Chemical Composition

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)= <b>0.271</b>	Compound Weight (g) Breakdown of 73 Material
Fe2O3	1309-37-1	67	0.1816	
ZnO	1314-13-2	14	0.0379	
MnO	1344-43-0	19	0.0515	

## Pb- Free Plated Flat Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)= <b>0.022</b>	Element Weight (g) Breakdown of Pb- Free Plated Flat Cu Wire
Cu	7440-50-8	94.8	0.02086	
Plating:				
Ni	7440-02-0	1.7	0.00037	
Sn	7440-31-5	3.5	0.00077	

## Parylene Coating

<u>Compound</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of Parylene (g)= <b>0.007</b>	Compound Weight (g) Breakdown of Parylene Coating
Parylene	28804-46-8	100	0.007	

## Calculated Maximum Levels of RoHS Restricted Substances Present in 73 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)= <b>0.271</b>	RoHS Impurity Substance Weight (g) Breakdown of 73 Material
Hexavalent chromium (Cr+6)	1000	0.00	0	
Cadmium (Cd)	100	3.70	1.0027E-06	
Mercury (Hg)	1000	0.10	2.71E-08	
Lead (Pb)	1000	8.25	2.23575E-06	
Polybrominated biphenyl (PBB)	1000	0.00	0	
Polybrominated diphenyl (PBDE)	1000	0.00	0	
Bis(2-Ethylhexyl) phthalate (DEHP)	1000	0.00	0	
Benzyl butyl phthalate (BBP)	1000	0.00	0	
Dibutyl phthalate (DBP)	1000	0.00	0	
Diisobutyl phthalate (DIBP)	1000	0.00	0	

### Supporting notes:

- P/N 2773021447 consists of:
  - core 73 Material Grade
  - wire Pb- Free Plated Flat Cu Wire
- Moisture Sensitivity Level (MSL)= 1
- Max Reflow Temp= 260 degC
- Max Time at Max Reflow Temp= 40 sec
- RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
- RoHS Conversion Date= 1/1/2005
- RoHS Compliance Marking is Contained on Shipping Labels